

DP-306458

**METHOD FOR SECURING CERAMIC STRUCTURES AND
FORMING ELECTRICAL CONNECTIONS ON THE SAME**

Abstract of the Disclosure

A new kinetic spray process is disclosed that enables one to secure a plurality of ceramic elements together quickly without the need for glues or other adhesives. The process finds special utilization in the formation of non-thermal plasma reactors wherein the kinetic spray process can be used to simultaneously secure the ceramic elements together and to form electrical connections between like electrodes in the non-thermal plasma reactor.